

ABSTRACT OF THE DISCLOSURE

A hybrid integrated circuit (IC) package substrate at least comprising a plurality of patterned conductive layers stacked over each other. The outermost patterned conductive layer has a plurality of bonding pads thereon. The hybrid IC package
5 substrate also has a plurality of dielectric layers respectively sandwiched between two neighboring patterned conductive layers. At least one of the dielectric layers is a ceramic dielectric layer and at least one of the remaining dielectric layers is an organic dielectric layer. There is also a plurality of vias passing through at least one of the dielectric layers for connecting at least two patterned conductive layers electrically.